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2823  
Atty. Docket No.: BU9-99-197

Response Transmittal

In re application of Enokawa, et al.

Serial No.: 09/599,783

Filed: 06/22/2000

For: METHOD FOR ETCHING A SEMICONDUCTOR SUBSTRATE  
USING GERMANIUM HARD MASK

Box No Fee

Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Sir:

Transmitted herewith for filing in the above-identified Application is a:

1. Response; and
2. Associate Power of Attorney.

☒ No additional fee is required.

☐ The fee has been calculated as shown below:

(Col. 1)		(Col. 2)		(Col. 3)
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on <u>June 11, 2002</u>  Heather Clark

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☒ Any additional filing fees required under 37 C.F.R. §1.16.

☒ Any patent application processing fees under 37 C.F.R. §1.17.

Date: June 11, 2002

Respectfully submitted,

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By   
Keith L. Jenkins  
Registration No.: 46,303

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AMENDMENT

Docket No. BU9-99-197

Applicant:	Furukawa, et al.	Docket No.:	BU9-99-197
Serial No.:	09/599,783	Group Art Unit:	2823
Filed:	06/22/2000	Examiner:	Maldonado, Julio J.
TITLE:	METHOD FOR ETCHING A SEMICONDUCTOR SUBSTRATE USING GERMANIUM HARD MASK		

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The Commissioner of Patents and Trademarks  
Washington, D.C. 20231

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Sir:

In response to the office action dated March 13, 2002, please amend the subject application as follows:

I HEREBY CERTIFY THAT THE CORRESPONDENCE TO WHICH THIS STATEMENT IS AFFIXED IS BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE, POSTAGE PAID, AS FIRST CLASS MAIL IN AN ENVELOPE ADDRESSED TO THE COMMISSIONER OF PATENTS AND TRADEMARKS, WASHINGTON, D.C., 20231, ON: June 11, 2002

SIGNED: Heather Clark

Heather Clark